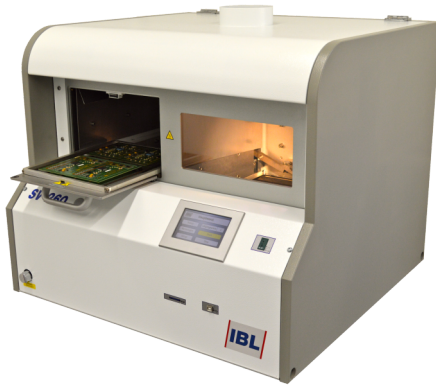


# SV260

Leading in Vapor Phase Technology

Economy Vapor Phase Soldering Machine for Small Series and Prototyping

**IBL**



## The Machine

The SV260 reflow vapor phase soldering machine is perfect for small volume production and offers superior solder quality. It is ideal for development, NPI and prototype production as well as for soldering BGAs and LGAs.

## Overview

- Table-top unit with front loading
- 2-chamber design for low consumption
- Oxygen free soldering
- No overheating of components
- No  $\Delta T$ 's throughout the assembly

## Standard Equipment / Specification

- Easy accessible loading and unloading area
- Integrated cooling fan for board cooling
- Fully automatic solder cycle
- Solder automatic
- Energy management system
- Fluid level check
- Observation window to process chamber
- Touchpanel
- SD card slot for data and program storage

## Special features

- Maintenance-free transport system (**patented**)
- Low fluid consumption with 2-chamber design and fluid recovery
- Program memory up to 16 programs
- Easy profil recording option
- **Exhaust connection**

## Options

- Adapter for double sided PCB boards
- ReSy, a device for repair of QFP's and BGA's
- Stainless steel grid for the workpiece carrier
- Closed-loop-chiller
- TE-Option for external profile monitoring
- USB profiling system
- Movable under-desk

Technical Data	SV260
Length (over all)	770 mm
Depth	710 mm
Height	680 mm
Weight	110 kg
Max. board size	300 x 260 x 70 mm
Liquid agent filling	3 kg
Water connection	1/2" / 2,5-5 bar / 1l /min
Max. heating capacity	2,1 kW
Ø power consumption/h	0,9 kW/h
Power supply	230 VAC, 50Hz, 2,2 KW
Main fuse	16 A, Typ "gL" or "C"

- Technical changes reserved -

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